Vishay Siliconix

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY							
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (TYP.) (nC)				
	0.760 at V _{GS} = -4.5 V	-0.45					
-20	1.040 at V _{GS} = -2.5 V	-0.40	1				
	1.500 at V _{GS} = -1.8 V	-0.32					

SC-89 (3 leads)



FEATURES

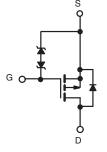
- TrenchFET® power MOSFET
- 100 % R_g tested
- Typical ESD protection: 1000 V (HBM)
- Fast switching speed
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>



FREE

APPLICATIONS

- Load / power switch for portable devices
- Drivers: relays, solenoids, displays
- · Battery operated systems



P-Channel MOSFET

Marking Code: 6 Ordering Information:

Si1013CX-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)					
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage	V_{DS}	-20	.,		
Gate-Source Voltage	V_{GS}	± 8	V		
Continuous Drain Current (T _{.I} = 150 °C)	T _A = 25 °C	I-	-0.45 ^{b, c}	Α	
Continuous Drain Current (1) = 150 C)	T _A = 70 °C	- I _D	-0.36 ^{b, c}		
Pulsed Drain Current (t = 300 µs)	I _{DM}	-1.5] A		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	-0.16 ^{b, c}		
Maximum Power Dissipation	T _A = 25 °C	- P _D	0.19 ^{b, c}	W	
iviaximum rower bissipation	T _A = 70 °C	-D	0.12 ^{b, c}] vv	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	-55 to +150	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum Junction-to-Ambient ^{a, b}	t ≤ 5 s	R_{thJA}	440	530	°C/W	
Maximum Junction-to-Ambient 4,7	Steady State		540	650		

Notes

- a. Maximum under steady state conditions is 650 °C/W.
- b. Surface mounted on 1" x 1" FR4 board.

S14-1601-Rev. B, 11-Aug-14

c. t = 5 s.



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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0, I _D = -250 μA	-20	-	_	V	
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J		-	-12	_	mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = -250 \mu A$	-	1.8	-		
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-0.4	-	-1	V	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 30	μΑ	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$	-	-	± 1		
		V _{DS} = -20 V, V _{GS} = 0 V	-	-	-1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V, T _J = 85 °C	-	-	-10	1	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} = \ge 5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-1.5	-	_	Α	
	(*)	$V_{GS} = -4.5 \text{ V}, I_D = -0.4 \text{ A}$	-	0.630	0.760		
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = -2.5 V, I _D = -0.2 A	-	0.865	1.040		
	, ,	V _{GS} = -1.8 V, I _D = -0.1 A	-	1.200	1.500		
Forward Transconductance	9fs	$V_{DS} = -10 \text{ V}, I_D = 0.4 \text{ A}$	-	1	-	S	
Dynamic ^b			l .		L	L	
Input Capacitance	C _{iss}		-	45	_		
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	15	-	pF	
Reverse Transfer Capacitance	C _{rss}		-	10	-		
Tabal Cata Observe		$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -0.4 \text{ A}$	-	1.65	5 2.50		
Total Gate Charge	Qg		-	1	2		
Gate-Source Charge	Q _{gs}	$V_{DS} = -0 \text{ V}, V_{GS} = -2.5 \text{ V}, I_D = -0.4$	-	0.2	-	nC	
Gate-Drain Charge	Q _{gd}		-	0.26	-		
Gate Resistance	R_g	f = 1 MHz	2.4	12	24	Ω	
Turn-On Delay Time	t _{d(on)}		-	9	18		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 33.3 \Omega$	-	10	20]	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -0.3 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	10	20		
Fall Time	t _f		-	8	16		
Turn-On Delay Time	t _{d(on)}		-	1	2	ns	
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 33.3 \Omega$	-	8	16		
Turn-Off DelayTime	t _{d(off)}	$I_D\cong$ -0.3 A, $V_{GEN}=$ -8 V, $R_g=$ 1 Ω	-	9	18		
Fall Time	t _f		-	5	10		
Drain-Source Body Diode Characteris	tics		•				
Pulse Diode Forward Current ^a	I _{SM}		-	-	-1.5	Α	
Body Diode Voltage	V_{SD}	I _S = -0.3 A	-	-0.8	-1.2	V	
Body Diode Reverse Recovery Time	t _{rr}		-	16	24	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1 000 4 41/11 400 4/		8	16	nC	
Reverse Recovery Fall Time	e Recovery Fall Time t_a $I_F = -0.3 \text{ A, dI/dt} = 100 \text{ A/}\mu\text{s}$		-	11	-	p.0	
Reverse Recovery Rise Time	t _b		-	5	-	ns	

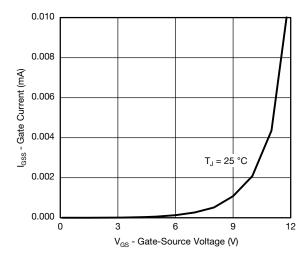
Notes

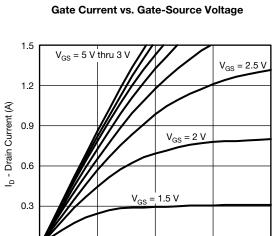
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



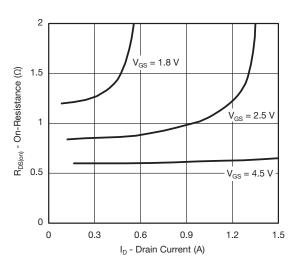
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



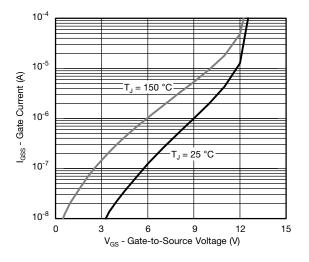


Output Characteristics

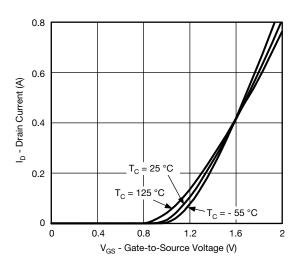
V_{DS} - Drain-to-Source Voltage (V)



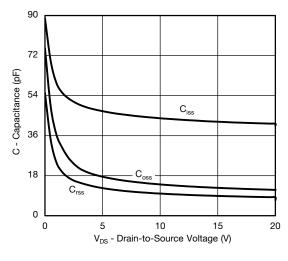
On-Resistance vs. Drain Current



Gate Current vs. Gate-Source Voltage



Transfer Characteristics

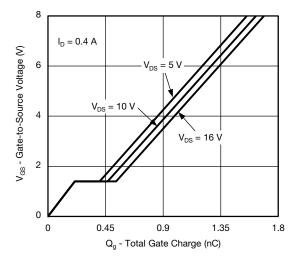


Capacitance

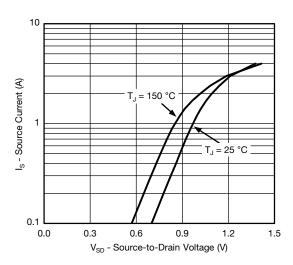
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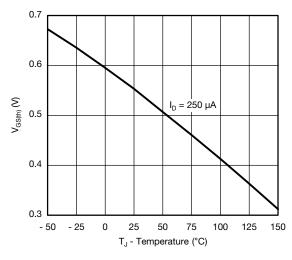
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



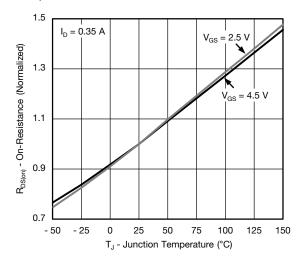
Gate Charge



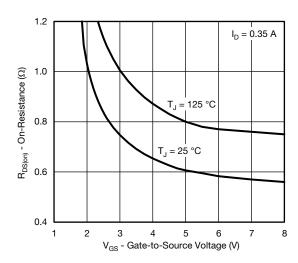
Source-Drain Diode Forward Voltage



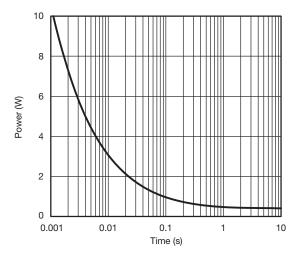
Threshold Voltage



On-Resistance vs. Junction Temperature



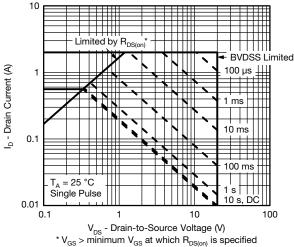
On-Resistance vs. Gate-to-Source Voltage



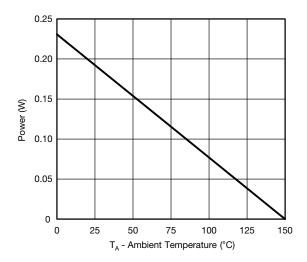
Single Pulse Power, Junction-to-Ambient



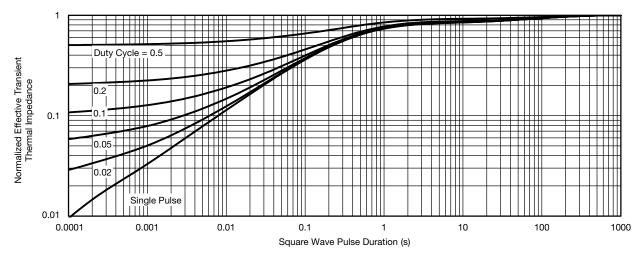
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







Power Derating, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient

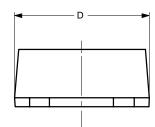
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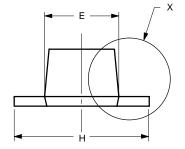


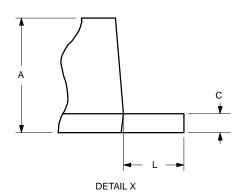


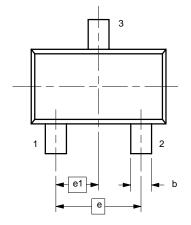
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SC89-3





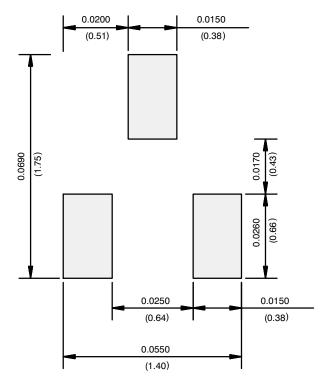




	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	0.60	0.80	0.024	0.031	
b	0.23	0.33	0.009	0.013	
С	0.10	0.20	0.004	0.008	
D	1.50	1.70	0.059	0.067	
Е	0.75	0.95	0.030	0.037	
е	1.00 BSC		0.040 BSC		
e ₁	0.50 BSC		0.020	BSC	
Н	1.50	1.70	0.059	0.067	
L	0.30	0.50	0.012	0.020	
ECN: S-03946—Rev. B, 09-Jul-01 DWG: 5869					



RECOMMENDED MINIMUM PADS FOR SC-89: 3-Lead



Recommended Minimum Pads Dimensions in Inches/(mm)

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